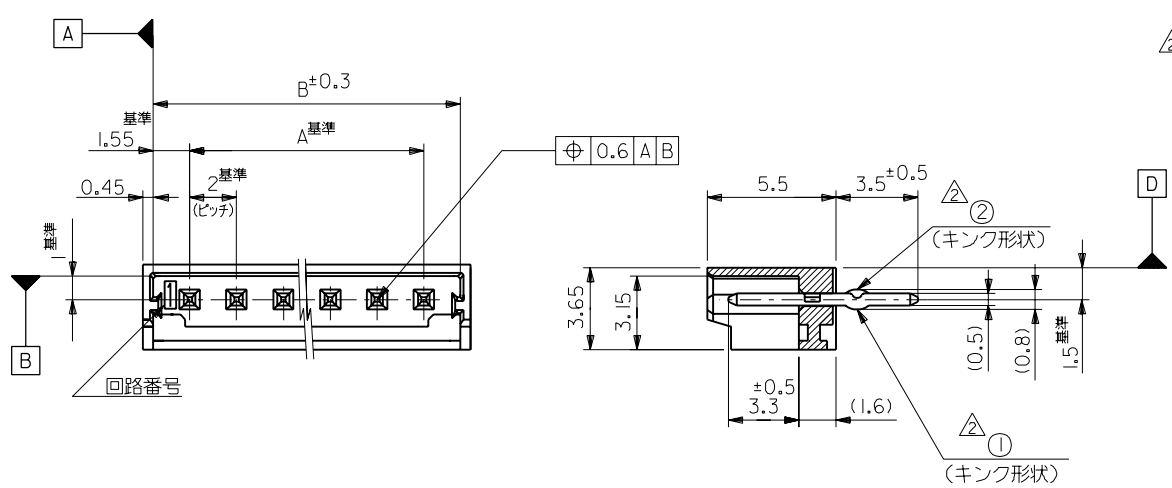


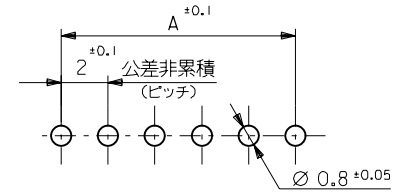
ENG. NO. SD-53253-\*\*\*10  
EDP NO.

MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING



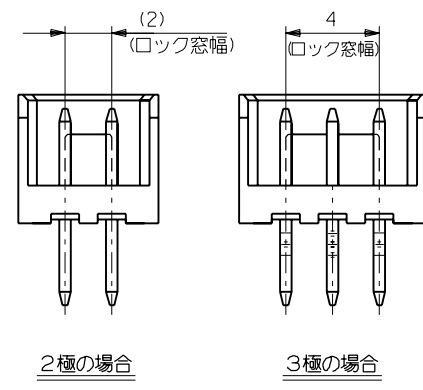
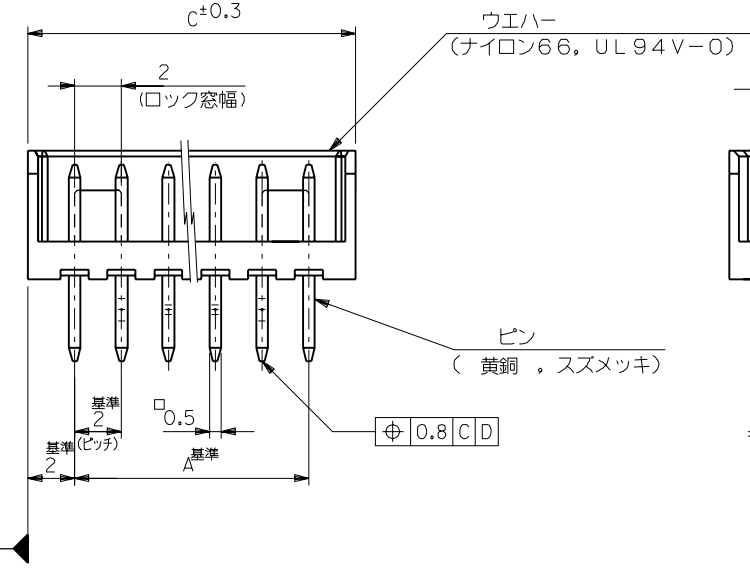
注 記  
1 炭合相手：51065-\*\*\*00  
△ キルクは下記表の位置及び形状に付加のこと。 2極はキルク無し。

回路番号 極数	1	2	3	4	5	N-2	N-1	N
6極以上	—	①	②	—	—	②	①	—
5極	①	②	—	②	①			
4極	①	②	②	①				
3極	①	②	①					



基板取付穴寸法 (参考)  
(t = 1.6)

32	31.1	28	53253-1510	15
30	29.1	26	-1410	14
28	27.1	24	-1310	13
26	25.1	22	-1210	12
24	23.1	20	-1110	11
22	21.1	18	-1010	10
20	19.1	16	-0910	9
18	17.1	14	-0810	8
16	15.1	12	-0710	7
14	13.1	10	-0610	6
12	11.1	8	-0510	5
10	9.1	6	-0410	4
8	7.1	4	-0310	3
6	5.1	2	53253-0210	2
C	B	A	ENG NO.	極数



角度 ANGLE	±3°				材料 MATERIAL	図中参照	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
30以上 OVER	+0.3				仕上げ FINISH	図中参照	
10以上 30未滿 UNDER	+0.25				適用電線範囲 WIRE RANGE	—	ENG. NO.
10未滿 UNDER	+0.2				被覆外径 INS. RANGE	—	SD-53253-***10
一般公差 GENERAL TOLERANCES					DRAWN BY 91/2/21 S. AIHARA	CHK'D BY 91/3/91 M. IRIKAWASHIMA	REV C
					REVISION RECORD	尺度 SCALE 5-1	TITLE 名称 NEW 2.0 WIRE TO BOARD CONN. WAFER ASS'Y (ST.)

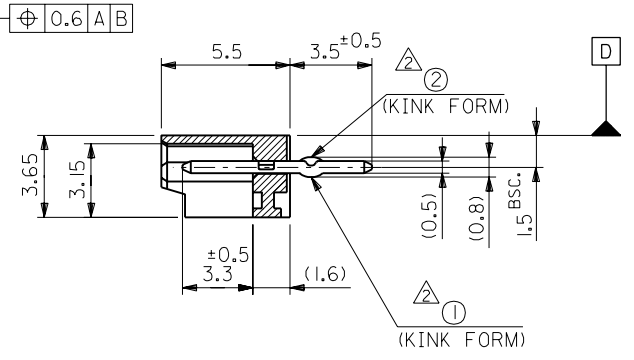
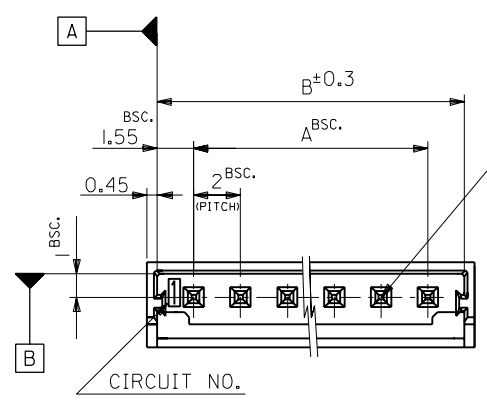
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MXJ-8

ENG. NO.  
SD-53253-\*\*\*10

EDP NO.

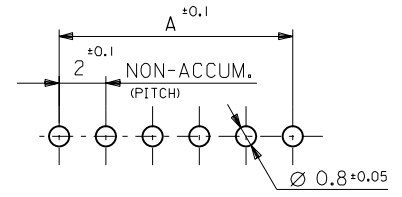
MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING



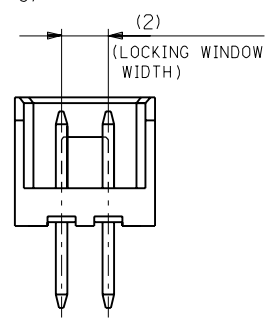
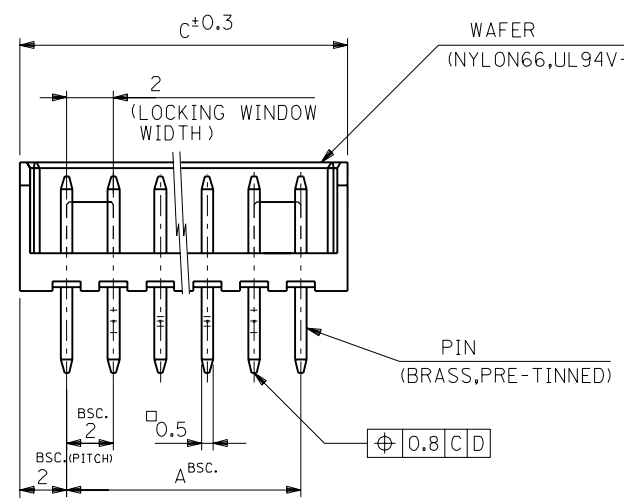
NOTES

1 MATES WITH: 51065-\*\*\*00  
 △KINK TO BE APPLIED AS FOLLOWS, 2 CIRCUIT HAS NO KINK

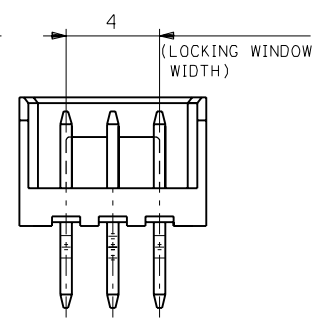
CKT NO.	1	2	3	4	5	N-2	N-1	N
MORE THAN 6 CKT	—	①	②	—	—	②	①	—
5 CKT	①	②	—	②	①	—	—	—
4 CKT	①	②	②	①	—	—	—	—
3 CKT	①	②	①	—	—	—	—	—



RECOMMENDED P.C. BOARD HOLE DIMENSION (REFERENCE)  
 (t = 1.6)



IN CASE OF 2 CIRCUIT WAFER



IN CASE OF 3 CIRCUIT WAFER

32	31.1	28	53253-1510	15
30	29.1	26	-1410	14
28	27.1	24	-1310	13
26	25.1	22	-1210	12
24	23.1	20	-1110	11
22	21.1	18	-1010	10
20	19.1	16	-0910	9
18	17.1	14	-0810	8
16	15.1	12	-0710	7
14	13.1	10	-0610	6
12	11.1	8	-0510	5
10	9.1	6	-0410	4
8	7.1	4	-0310	3
6	5.1	2	53253-0210	2
C	B	A	ENG NO.	CKT

角度 ANGLE	+3°								
30 以上 OVER	+0.3								
10 以上 30 未満 UNDER	+0.25								
10 未満 UNDER	+0.2								
一般公差 GENERAL TOLERANCES									
記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE						
REVISION RECORD				REVISED (J20439)	1.1	M.S	92/7/17		
REVISION RECORD				REVISED (J10095)	1.1	S	91/2/28		
REVISION RECORD				REVISED (J00016)	1.1		90/1/11		
REVISION RECORD				PROPOSED (J91084)	1.1		89/12/20		
REVISION RECORD				PROPOSED (J91084)	1.1		89/12/20		
REVISION RECORD				PROPOSED (J91084)	1.1		89/12/20		

材料 MATERIAL REFER TO DRAWING

仕上げ FINISH REFER TO DRAWING

適用電線範囲 WIRE RANGE

被覆外径 INS. RANGE

DRAWN BY 89/9/21 S.AIHARA

CHK'D BY 89/9/21 M.FURUSHIMA

APP'D BY 89/9/21 M.EMONOMOTO

材料 MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社

EDP NO.

ENG. NO. SD-53253-\*\*\*10

REV C

TITLE 名称 NEW 2.0 WIRE TO BOARD CONN. WAFER ASS'Y (ST.)

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